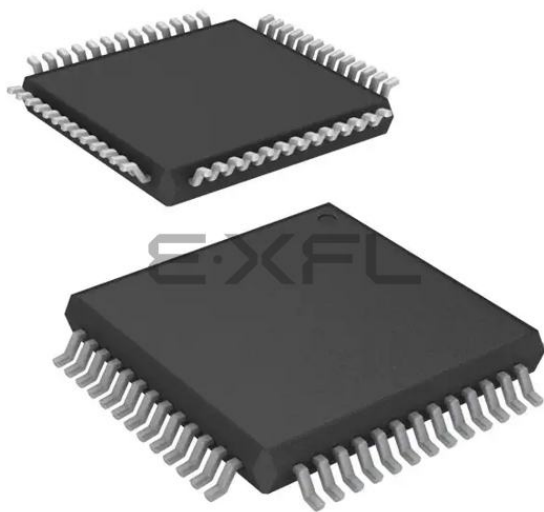




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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I ² C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, Voltage Detect, WDT
Number of I/O	41
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	52-LQFP
Supplier Device Package	52-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f21254snfp-v2

1. Overview

These MCUs are fabricated using a high-performance silicon gate CMOS process, embedding the R8C/Tiny Series CPU core, and are packaged in a 52-pin molded-plastic LQFP or a 64-pin molded-plastic FLGA. It implements sophisticated instructions for a high level of instruction efficiency. With 1 Mbyte of address space, they are capable of executing instructions at high speed.

Furthermore, the R8C/25 Group has on-chip data flash (1 KB x 2 blocks).

The difference between the R8C/24 Group and R8C/25 Group is only the presence or absence of data flash. Their peripheral functions are the same.

1.1 Applications

Electronic household appliances, office equipment, audio equipment, consumer products, etc.

1.2 Performance Overview

Table 1.1 outlines the Functions and Specifications for R8C/24 Group and Table 1.2 outlines the Functions and Specifications for R8C/25 Group.

Table 1.1 Functions and Specifications for R8C/24 Group

Item		Specification
CPU	Number of fundamental instructions	89 instructions
	Minimum instruction execution time	50 ns (f(XIN) = 20 MHz, VCC = 3.0 to 5.5 V) 100 ns (f(XIN) = 10 MHz, VCC = 2.7 to 5.5 V) 200 ns (f(XIN) = 5 MHz, VCC = 2.2 to 5.5 V)
	Operating mode	Single-chip
	Address space	1 Mbyte
	Memory capacity	Refer to Table 1.3 Product Information for R8C/24 Group
Peripheral Functions	Ports	I/O ports: 41 pins, Input port: 3 pins
	LED drive ports	I/O ports: 8 pins
	Timers	Timer RA: 8 bits × 1 channel Timer RB: 8 bits × 1 channel (Each timer equipped with 8-bit prescaler) Timer RD: 16 bits × 2 channels (Input capture and output compare circuits) Timer RE: With real-time clock and compare match function
	Serial interfaces	2 channels (UART0, UART1) Clock synchronous serial I/O, UART
	Clock synchronous serial interface	1 channel I ² C bus Interface ⁽¹⁾ Clock synchronous serial I/O with chip select
	LIN module	Hardware LIN: 1 channel (timer RA, UART0)
	A/D converter	10-bit A/D converter: 1 circuit, 12 channels
	Watchdog timer	15 bits × 1 channel (with prescaler) Reset start selectable
	Interrupts	Internal: 11 sources, External: 5 sources, Software: 4 sources, Priority levels: 7 levels
	Clock	Clock generation circuits
		3 circuits • XIN clock generation circuit (with on-chip feedback resistor) • On-chip oscillator (high speed, low speed) High-speed on-chip oscillator has a frequency adjustment function • XCIN clock generation circuit (32 kHz)
		Real-time clock (timer RE)
	Oscillation stop detection function	XIN clock oscillation stop detection function
	Voltage detection circuit	On-chip
	Power-on reset circuit	On-chip
Electrical Characteristics	Supply voltage	VCC = 3.0 to 5.5 V (f(XIN) = 20 MHz) VCC = 2.7 to 5.5 V (f(XIN) = 10 MHz) VCC = 2.2 to 5.5 V (f(XIN) = 5 MHz)
	Current consumption	Typ. 10 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 6 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 2.0 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 0.7 μA (VCC = 3.0 V, stop mode)
Flash Memory	Programming and erasure voltage	VCC = 2.7 to 5.5 V
	Programming and erasure endurance	100 times
Operating Ambient Temperature		-20 to 85°C (N version)
		-40 to 85°C (D version) ⁽²⁾
		-20 to 105°C (Y version) ⁽³⁾
Package		52-pin molded-plastic LQFP
		64-pin molded-plastic FLGA

NOTES:

1. I²C bus is a trademark of Koninklijke Philips Electronics N. V.
2. Specify the D version if D version functions are to be used.
3. Please contact Renesas Technology sales offices for the Y version.

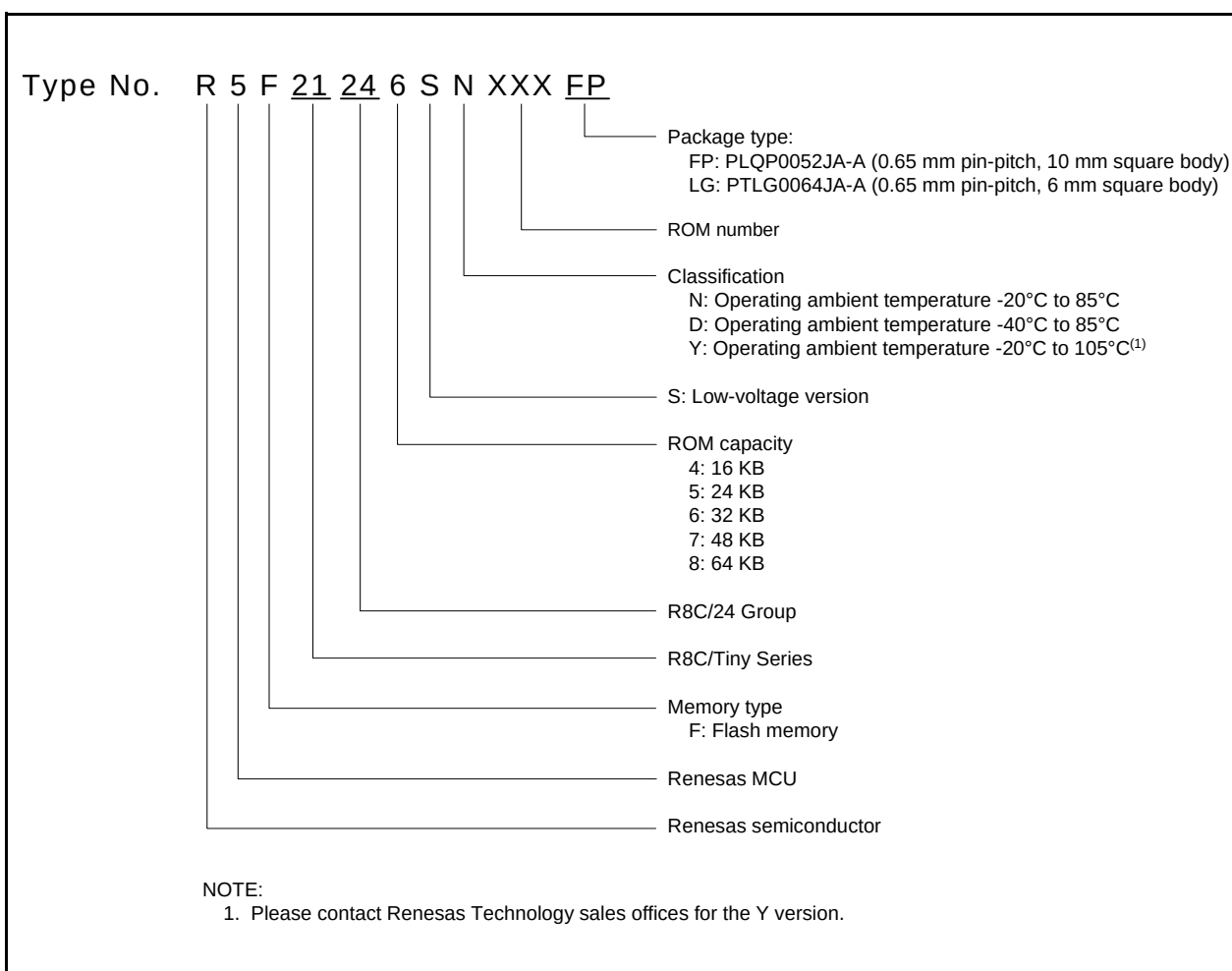


Figure 1.2 Type Number, Memory Size, and Package of R8C/24 Group

Table 1.4 Product Information for R8C/25 Group

Current of Feb. 2008

Type No.	ROM Capacity		RAM Capacity	Package Type	Remarks
	Program ROM	Data flash			
R5F21254SNFP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLQP0052JA-A	N version Blank product
R5F21255SNFP	24 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F21256SNFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F21257SNFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0052JA-A	
R5F21258SNFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0052JA-A	
R5F21254SNLG	16 Kbytes	1 Kbyte × 2	1 Kbyte	PTLG0064JA-A	
R5F21256SNLG	32 Kbytes	1 Kbyte × 2	2 Kbytes	PTLG0064JA-A	D version Blank product
R5F21254SDFP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLQP0052JA-A	
R5F21255SDFP	24 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F21256SDFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F21257SDFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0052JA-A	
R5F21258SDFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0052JA-A	
R5F21254SNXXXFP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLQP0052JA-A	N version Factory programming product ⁽¹⁾
R5F21255SNXXXFP	24 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F21256SNXXXFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F21257SNXXXFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0052JA-A	
R5F21258SNXXXFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0052JA-A	
R5F21254SNXXXLG	16 Kbytes	1 Kbyte × 2	1 Kbyte	PTLG0064JA-A	
R5F21256SNXXXLG	32 Kbytes	1 Kbyte × 2	2 Kbytes	PTLG0064JA-A	D version Factory programming product ⁽¹⁾
R5F21254SDXXXFP	16 Kbytes	1 Kbyte × 2	1 Kbyte	PLQP0052JA-A	
R5F21255SDXXXFP	24 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F21256SDXXXFP	32 Kbytes	1 Kbyte × 2	2 Kbytes	PLQP0052JA-A	
R5F21257SDXXXFP	48 Kbytes	1 Kbyte × 2	2.5 Kbytes	PLQP0052JA-A	
R5F21258SDXXXFP	64 Kbytes	1 Kbyte × 2	3 Kbytes	PLQP0052JA-A	

NOTE:

1. The user ROM is programmed before shipment.

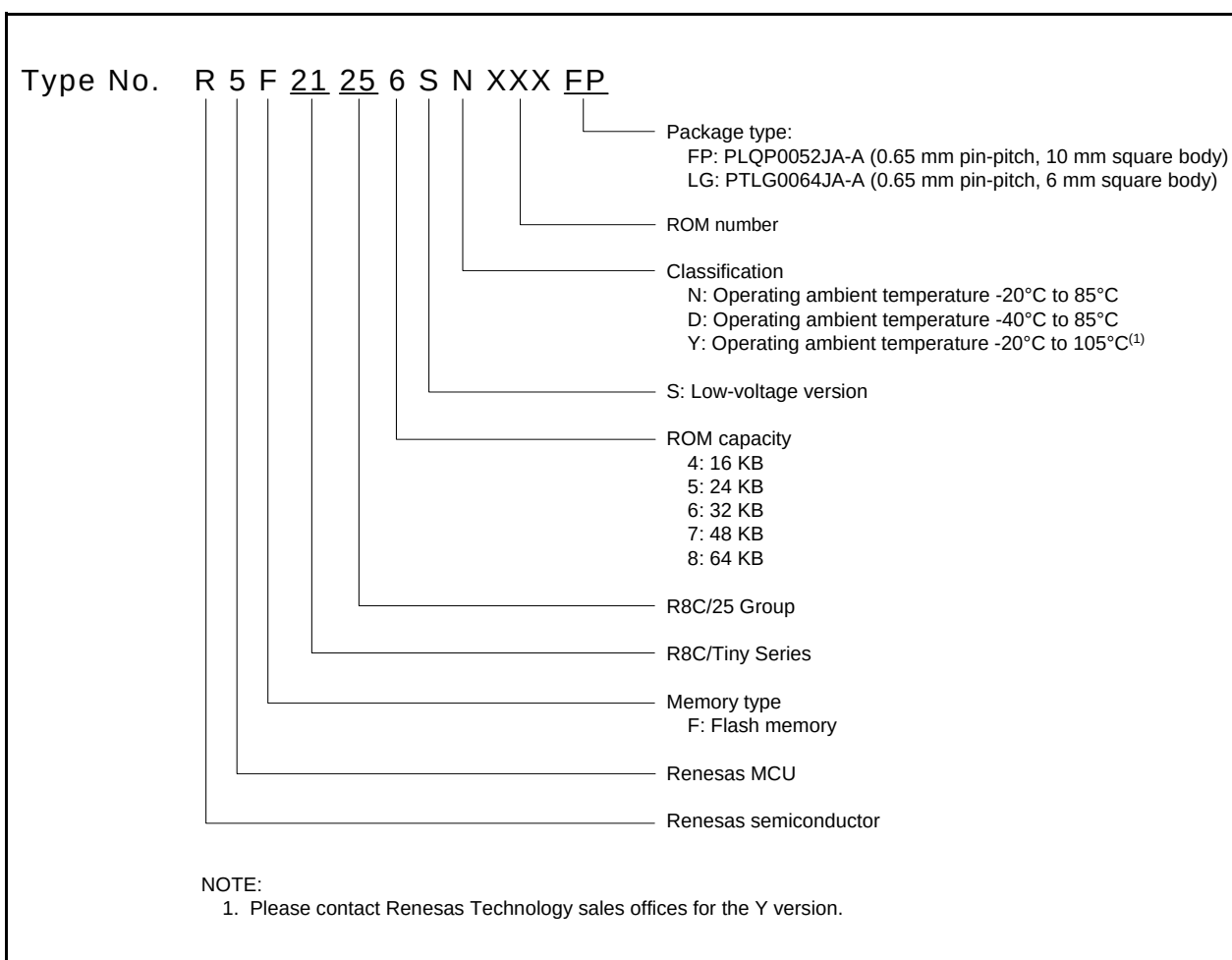


Figure 1.3 Type Number, Memory Size, and Package of R8C/25 Group

2. Central Processing Unit (CPU)

Figure 2.1 shows the CPU Registers. The CPU contains 13 registers. R0, R1, R2, R3, A0, A1, and FB configure a register bank. There are two sets of register bank.

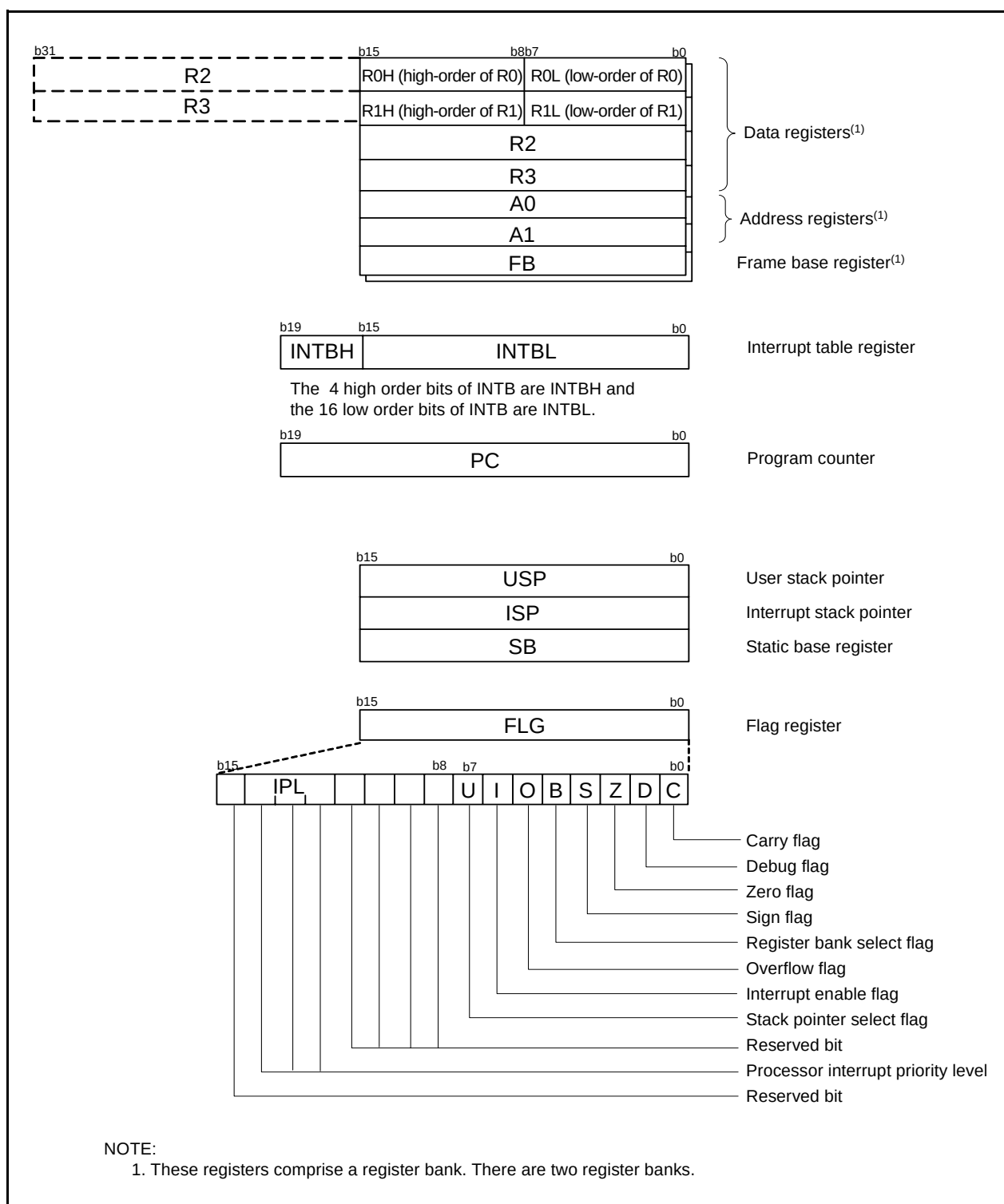


Figure 2.1 CPU Registers

2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.

Interrupt are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.

The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has higher priority than IPL, the interrupt is enabled.

2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

3. Memory

3.1 R8C/24 Group

Figure 3.1 is a Memory Map of R8C/24 Group. The R8C/24 group has 1 Mbyte of address space from addresses 00000h to FFFFFh.

The internal ROM is allocated lower addresses, beginning with address 0FFFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. They store the starting address of each interrupt routine.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 2-Kbyte internal RAM area is allocated addresses 00400h to 00BFFh. The internal RAM is used not only for storing data but also for calling subroutines and as stacks when interrupt requests are acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh. The peripheral function control registers are allocated here. All addresses within the SFR, which have nothing allocated are reserved for future use and cannot be accessed by users.

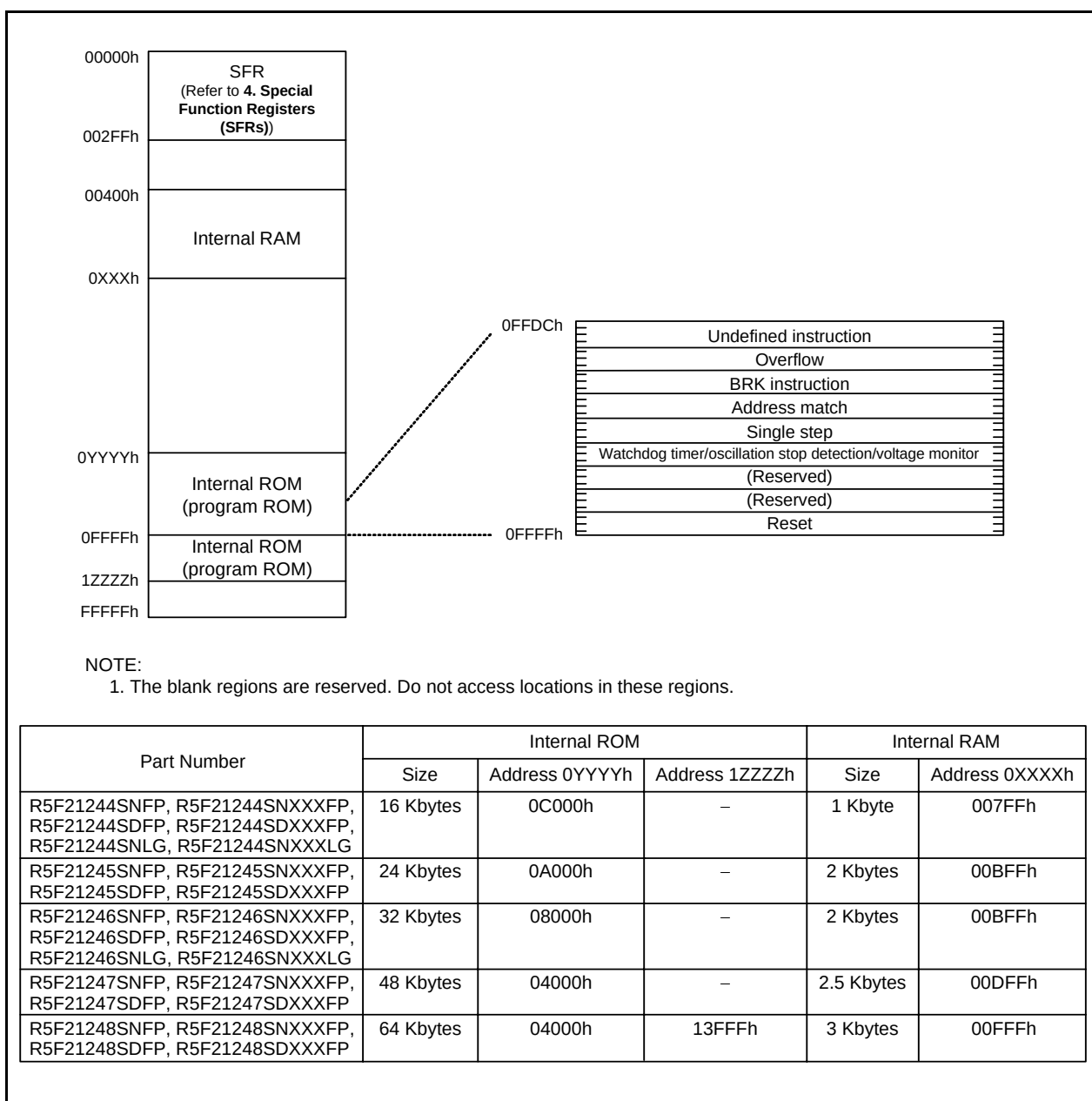


Figure 3.1 Memory Map of R8C/24 Group

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.7 list the special function registers.

Table 4.1 SFR Information (1)(1)

Address	Register	Symbol	After reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	01101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h			
0009h			
000Ah	Protect Register	PRCR	00h
000Bh			
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDC	00X11111b
0010h	Address Match Interrupt Register 0	RMAD0	00h
0011h			00h
0012h			00h
0013h	Address Match Interrupt Enable Register	AIER	00h
0014h	Address Match Interrupt Register 1	RMAD1	00h
0015h			00h
0016h			00h
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b ⁽⁶⁾
001Dh			
001Eh			
001Fh			
0020h			
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h			
0027h			
0028h	Clock Prescaler Reset Flag	CPSRF	00h
0029h	High-Speed On-Chip Oscillator Control Register 4	FRA4	When shipping
002Ah			
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When shipping
002Ch	High-Speed On-Chip Oscillator Control Register 7	FRA7	When shipping
0030h			
0031h	Voltage Detection Register 1 ⁽²⁾	VCA1	00001000b
0032h	Voltage Detection Register 2 ⁽²⁾	VCA2	00h ⁽³⁾ 00100000b ⁽⁴⁾
0033h			
0034h			
0035h			
0036h	Voltage Monitor 1 Circuit Control Register ⁽⁵⁾	VW1C	00001000b
0037h	Voltage Monitor 2 Circuit Control Register ⁽⁵⁾	VW2C	00h
0038h	Voltage Monitor 0 Circuit Control Register ⁽²⁾	VW0C	0000X000b ⁽³⁾ 0100X001b ⁽⁴⁾
0039h			
003Ah			
003Eh			
003Fh			

X: Undefined

NOTES:

1. The blank regions are reserved. Do not access locations in these regions.
2. Software reset, watchdog timer reset, and voltage monitor 1 reset or voltage monitor 2 reset do not affect this register.
3. The LVD0ON bit in the OFS register is set to 1 and hardware reset.
4. Power-on reset, voltage monitor 0 reset or the LVD0ON bit in the OFS register is set to 0, and hardware reset.
5. Software reset, watchdog timer reset, and voltage monitor 1 reset or voltage monitor 2 reset do not affect b2 and b3.
6. The CSPROINI bit in the OFS register is set to 0.

Table 4.4 SFR Information (4)⁽¹⁾

Address	Register	Symbol	After reset
00C0h	A/D Register	AD	XXh
00C1h			XXh
00C2h			
00C3h			
00C4h			
00C5h			
00C6h			
00C7h			
00C8h			
00C9h			
00CAh			
00CBh			
00CCh			
00CDh			
00CEh			
00CFh			
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Control Register 2	ADCON2	00h
00D5h			
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h	Port P2 Drive Capacity Control Register	P2DRR	00h
00F5h	UART1 Function Select Register	U1SR	XXh
00F6h			
00F7h			
00F8h	Port Mode Register	PMR	00h
00F9h	External Input Enable Register	INTEN	00h
00FAh	INT Input Filter Select Register	INTF	00h
00FBh	Key Input Enable Register	KIEN	00h
00FCh	Pull-Up Control Register 0	PUR0	00h
00FDh	Pull-Up Control Register 1	PUR1	XX00XX00b
00FEh			
00FFh			

X: Undefined

NOTE:

1. The blank regions are reserved. Do not access locations in these regions.

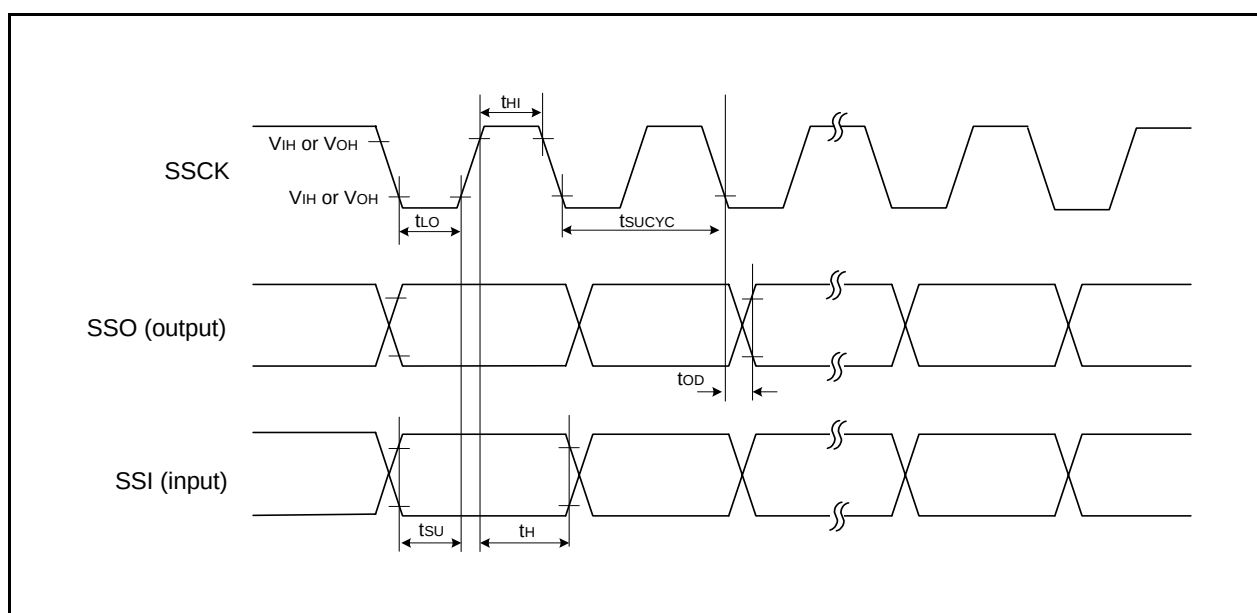
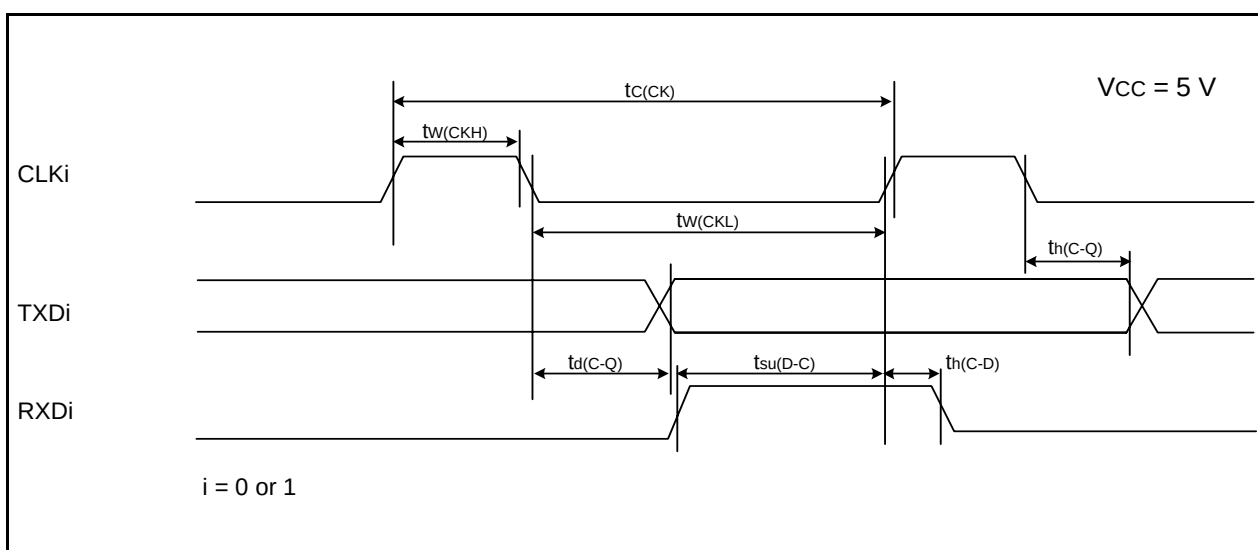


Figure 5.6 I/O Timing of Clock Synchronous Serial I/O with Chip Select (Clock Synchronous Communication Mode)

Table 5.20 Serial Interface

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(CK)}$	CLKi input cycle time	200	—	ns
$t_{w(CKH)}$	CLKi input "H" width	100	—	ns
$t_{w(CKL)}$	CLKi input "L" width	100	—	ns
$t_{d(C-Q)}$	TXDi output delay time	—	50	ns
$t_{h(C-Q)}$	TXDi hold time	0	—	ns
$t_{su(D-C)}$	RXDi input setup time	50	—	ns
$t_{h(C-D)}$	RXDi input hold time	90	—	ns

i = 0 or 1

**Figure 5.10 Serial Interface Timing Diagram when Vcc = 5 V****Table 5.21 External Interrupt $\overline{INTi}$ (i = 0 to 3) Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{w(INH)}$	$\overline{INT0}$ input "H" width	250 ⁽¹⁾	—	ns
$t_{w(INL)}$	$\overline{INT0}$ input "L" width	250 ⁽²⁾	—	ns

NOTES:

1. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input HIGH width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.
2. When selecting the digital filter by the $\overline{INTi}$ input filter select bit, use an $\overline{INTi}$ input LOW width of either (1/digital filter clock frequency × 3) or the minimum value of standard, whichever is greater.

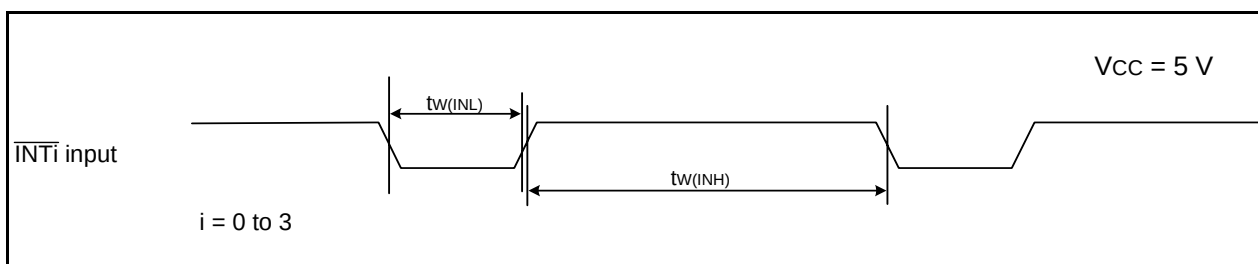
**Figure 5.11 External Interrupt $\overline{INTi}$ Input Timing Diagram when Vcc = 5 V**

Table 5.22 Electrical Characteristics (3) [Vcc = 3 V]

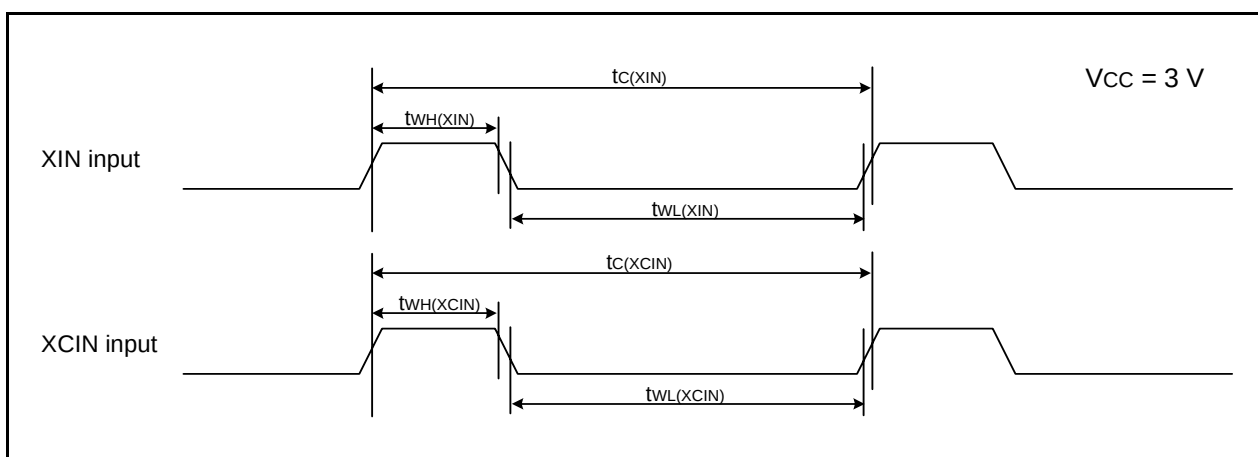
Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
VOH	Output "H" voltage	Except P2_0 to P2_7, XOUT	IOH = -1 mA		Vcc - 0.5	–	Vcc	V
		P2_0 to P2_7	Drive capacity HIGH	IOH = -5 mA	Vcc - 0.5	–	Vcc	V
			Drive capacity LOW	IOH = -1 mA	Vcc - 0.5	–	Vcc	V
		XOUT	Drive capacity HIGH	IOH = -0.1 mA	Vcc - 0.5	–	Vcc	V
			Drive capacity LOW	IOH = -50 μ A	Vcc - 0.5	–	Vcc	V
VOL	Output "L" voltage	Except P2_0 to P2_7, XOUT	IOL = 1 mA		–	–	0.5	V
		P2_0 to P2_7	Drive capacity HIGH	IOL = 5 mA	–	–	0.5	V
			Drive capacity LOW	IOL = 1 mA	–	–	0.5	V
		XOUT	Drive capacity HIGH	IOL = 0.1 mA	–	–	0.5	V
			Drive capacity LOW	IOL = 50 μ A	–	–	0.5	V
VT+-VT-	Hysteresis	$\overline{\text{INT0}}, \overline{\text{INT1}}, \overline{\text{INT2}}, \overline{\text{INT3}}, \text{KI0}, \text{KI1}, \text{KI2}, \text{KI3}, \text{TRAIO}, \text{RXD0}, \text{RXD1}, \text{CLK0}, \text{CLK1}, \text{SSI}, \text{SCL}, \text{SDA}, \text{SSO}$			0.1	0.3	–	V
		$\overline{\text{RESET}}$			0.1	0.4	–	V
I _{IH}	Input "H" current		VI = 3 V, Vcc = 3V		–	–	4.0	μ A
I _{IL}	Input "L" current		VI = 0 V, Vcc = 3V		–	–	-4.0	μ A
RPULLUP	Pull-up resistance		VI = 0 V, Vcc = 3V		66	160	500	k Ω
R _{FXIN}	Feedback resistance	XIN			–	3.0	–	M Ω
R _{FXCIN}	Feedback resistance	XCIN			–	18	–	M Ω
V _{RAM}	RAM hold voltage		During stop mode		1.8	–	–	V

NOTE:

- Vcc = 2.7 to 3.3 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 10 MHz, unless otherwise specified.

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 3\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{op} = 25^{\circ}\text{C}$) [$V_{CC} = 3\text{ V}$]****Table 5.24 XIN Input, XCIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	100	–	ns
$t_{WH(XIN)}$	XIN input “H” width	40	–	ns
$t_{WL(XIN)}$	XIN input “L” width	40	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

**Figure 5.12 XIN Input and XCIN Input Timing Diagram when $V_{CC} = 3\text{ V}$** **Table 5.25 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	300	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	120	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	120	–	ns

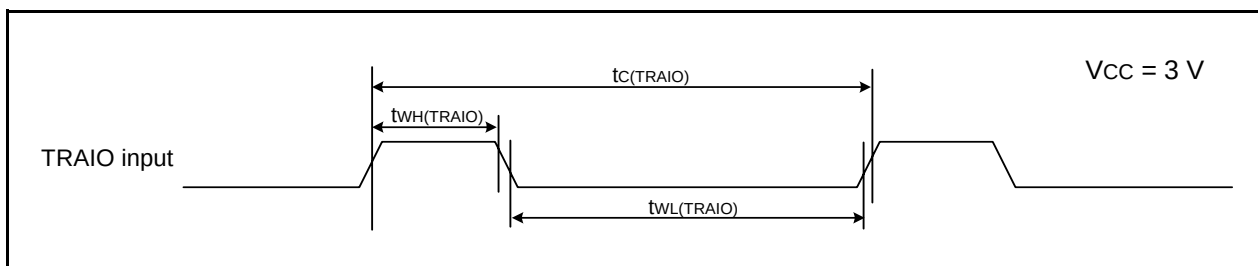
**Figure 5.13 TRAIO Input Timing Diagram when $V_{CC} = 3\text{ V}$**

Table 5.28 Electrical Characteristics (5) [V_{CC} = 2.2 V]

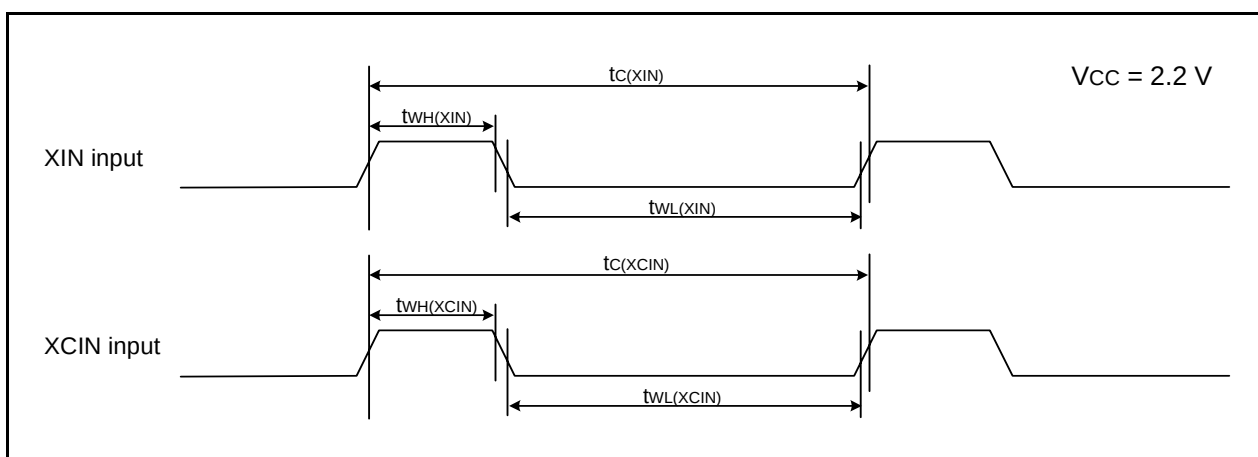
Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Except P2_0 to P2_7, XOUT	I _{OH} = -1 mA		V _{CC} - 0.5	–	V _{CC}	V
		P2_0 to P2_7	Drive capacity HIGH	I _{OH} = -2 mA	V _{CC} - 0.5	–	V _{CC}	V
			Drive capacity LOW	I _{OH} = -1 mA	V _{CC} - 0.5	–	V _{CC}	V
		XOUT	Drive capacity HIGH	I _{OH} = -0.1 mA	V _{CC} - 0.5	–	V _{CC}	V
			Drive capacity LOW	I _{OH} = -50 μA	V _{CC} - 0.5	–	V _{CC}	V
V _{OL}	Output "L" voltage	Except P2_0 to P2_7, XOUT	I _{OL} = 1 mA		–	–	0.5	V
		P2_0 to P2_7	Drive capacity HIGH	I _{OL} = 2 mA	–	–	0.5	V
			Drive capacity LOW	I _{OL} = 1 mA	–	–	0.5	V
		XOUT	Drive capacity HIGH	I _{OL} = 0.1 mA	–	–	0.5	V
			Drive capacity LOW	I _{OL} = 50 μA	–	–	0.5	V
V _{T+} -V _{T-}	Hysteresis	$\overline{\text{INT0}}, \overline{\text{INT1}}, \overline{\text{INT2}}, \overline{\text{INT3}}, \text{KI0}, \text{KI1}, \text{KI2}, \text{KI3}, \text{TRAIO}, \text{RXD0}, \text{RXD1}, \text{CLK0}, \text{CLK1}, \text{SSI}, \text{SCL}, \text{SDA}, \text{SSO}$			0.05	0.3	–	V
		$\overline{\text{RESET}}$			0.05	0.15	–	V
I _{IH}	Input "H" current		V _I = 2.2 V		–	–	4.0	μA
I _{IL}	Input "L" current		V _I = 0 V		–	–	-4.0	μA
R _{PULLUP}	Pull-up resistance		V _I = 0 V		100	200	600	kΩ
R _{FXIN}	Feedback resistance	XIN			–	5	–	MΩ
R _{FXCIN}	Feedback resistance	XCIN			–	35	–	MΩ
V _{RAM}	RAM hold voltage		During stop mode		1.8	–	–	V

NOTE:

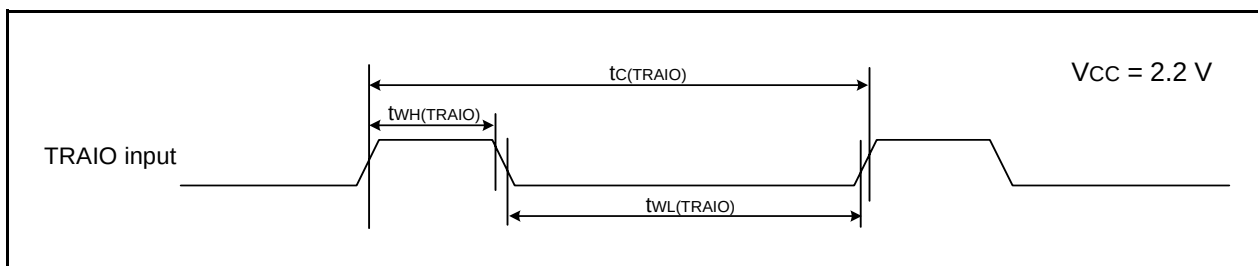
- V_{CC} = 2.2 V at T_{opr} = -20 to 85°C (N version) / -40 to 85°C (D version), f(XIN) = 5 MHz, unless otherwise specified.

Timing requirements**(Unless Otherwise Specified: $V_{CC} = 2.2\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = 25^\circ\text{C}$) [$V_{CC} = 2.2\text{ V}$]****Table 5.30 XIN Input, XCIN Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XIN)}$	XIN input cycle time	200	–	ns
$t_{WH(XIN)}$	XIN input “H” width	90	–	ns
$t_{WL(XIN)}$	XIN input “L” width	90	–	ns
$t_{c(XCIN)}$	XCIN input cycle time	14	–	μs
$t_{WH(XCIN)}$	XCIN input “H” width	7	–	μs
$t_{WL(XCIN)}$	XCIN input “L” width	7	–	μs

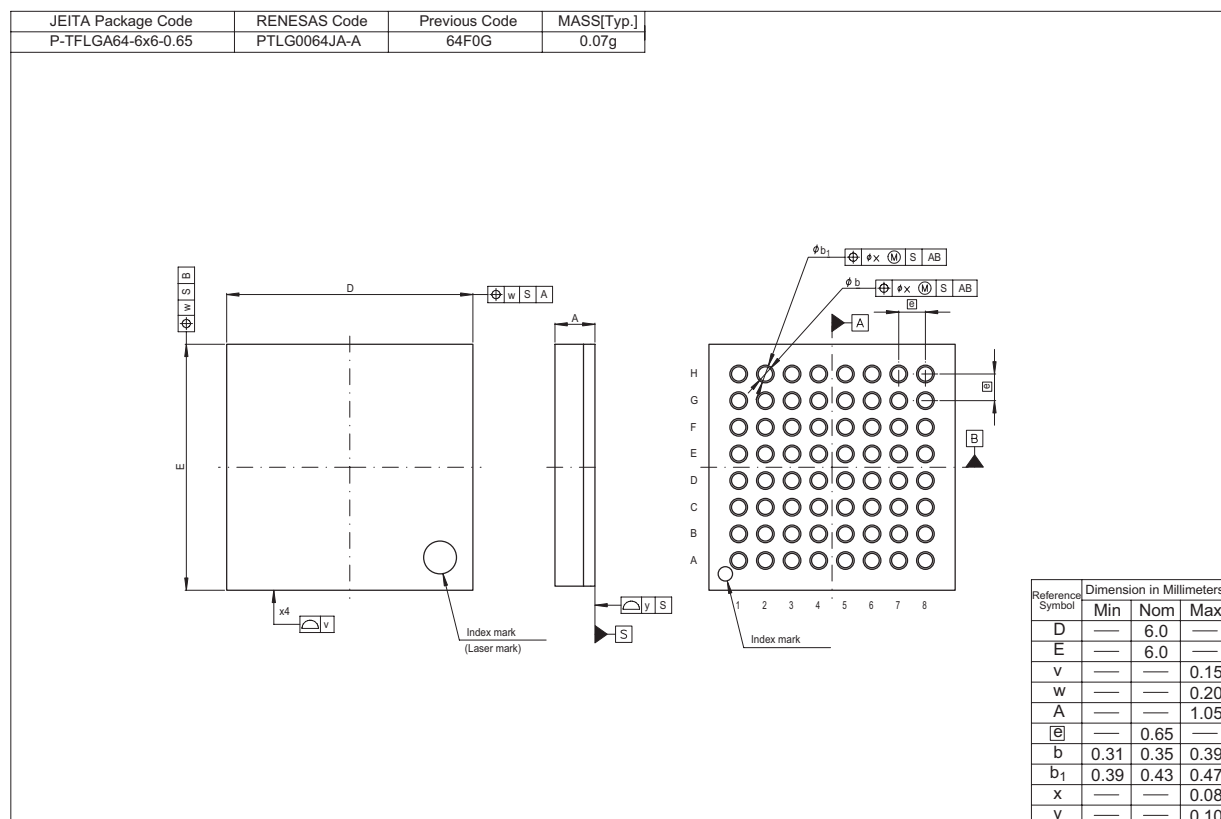
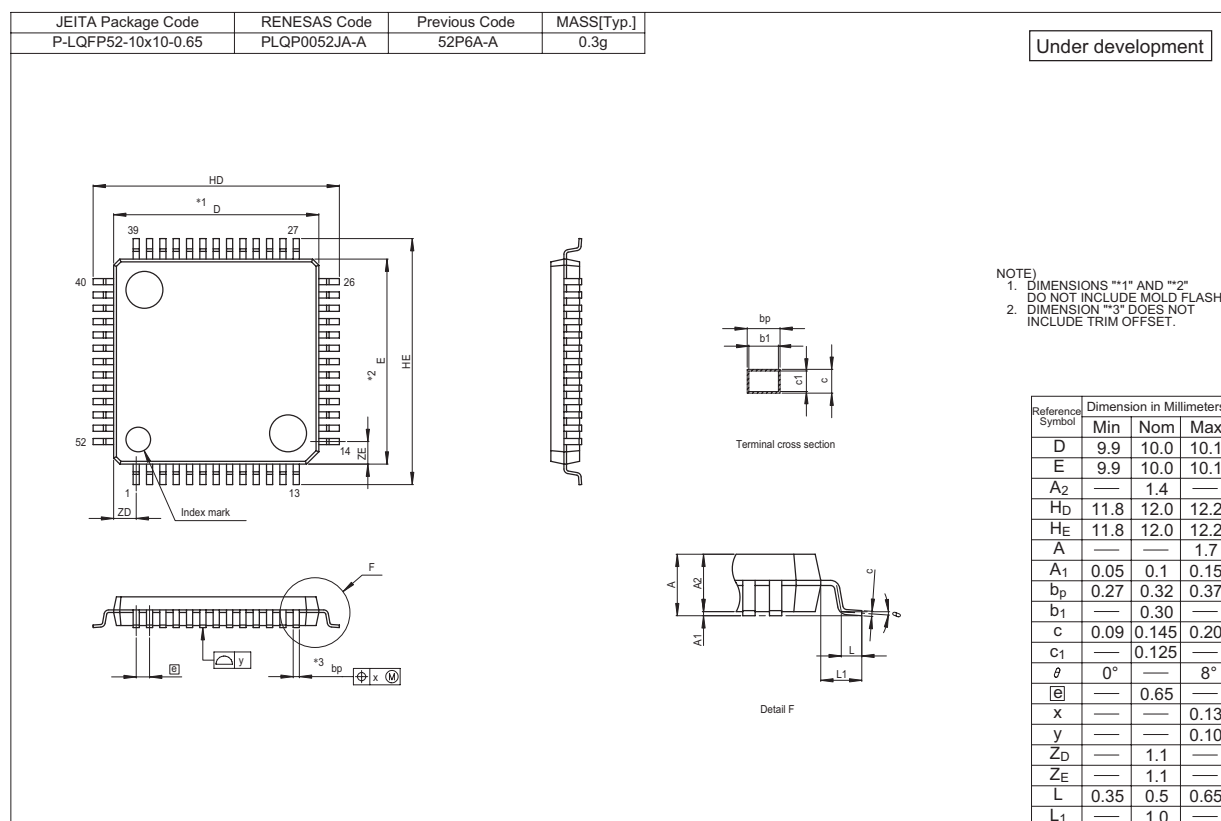
**Figure 5.16 XIN Input and XCIN Input Timing Diagram when $V_{CC} = 2.2\text{ V}$** **Table 5.31 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	500	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	200	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	200	–	ns

**Figure 5.17 TRAIO Input Timing Diagram when $V_{CC} = 2.2\text{ V}$**

Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Technology website.



REVISION HISTORY	R8C/24 Group, R8C/25 Group Datasheet
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Rev.	Date	Description	
		Page	Summary
0.01	Sep 17, 2004	-	First Edition issued
0.02	Dec 10, 2004	All pages 2, 3 4 5, 6 7 8 9 15 16 19	Part Number revised. R8C/26 → R8C/24, R8C/27 → R8C/25 Table 1.1 R8C/24 Group Performance, Table 1.2 R8C/25 Group Performance - Serial Interface: I²C Bus Interface and Chip-select clock synchronous (SSU) added. - LIN Module added. - Interrupt: Internal factors revised; 10 → 11 - Note on Operating Ambient Temperature added. Figure 1.1 Block Diagram - LIN Module added. - Chip-select clock synchronous (SSU) is added to I²C Bus Interface. Table 1.3 Product Information of R8C/24 Group, Table 1.4 Product Information of R8C/25 Group Date and Development state revised. Figure 1.4 Pin Assignment P3_5/SCL → P3_5/SCL/SSCK, P3_3 → P3_3/SSI, P3_4/SDA → P3_4/SDA/SCS, P3_7 → P3_7/SSO, VSS/AVSS → VSS, XIN/P4_6 → P4_6/XIN, VCC/AVSS → VCC 12pin P1_7/TRAO/INT1 to 22pin P1_0/KIO/AN8 → 20pin P1_7/TRAO/INT1 to 30pin P1_0/KIO/AN8 Table 1.5 Pin Description - Analog Power Supply Input eliminated. - SSU added. Table 1.6 Pin Name Information by Pin Number added. Table 4.1 SFR Information (1) - 0031h: Voltage Detection Register 1 → Voltage Detection <u>A</u> Register 1 - 0032h: Voltage Detection Register 1 → Voltage Detection <u>A</u> Register 2 01000001b → 00100001b (Note 4) - 0036h: "(3), 01000001b (4)" eliminated. - 0038h: Voltage Monitor 0 Control Register (2), VW0C, 00001000b (3), 01000001b (4) added. Table 4.2 SFR Information (2) - 0048h: Timer RD0 Interrupt Control Register, RD0IC, XXXXX000b added. - 0049h: Timer RD Interrupt Control Register, RDIC → Timer RD1 Interrupt Control Register, RD1IC - 004Fh: IIC Interrupt Control Register, IIC → IIC/SSU Interrupt Control Register, IIC2IC Table 4.5 SFR Information (3) - 0106h: LIN Control Register, LINCR, 00h added. - 0107h: LIN Status Register, LINST, 00h added.

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Rev.	Date	Description	
		Page	Summary
0.40	Jan 24, 2006	15	Table 4.1 SFR Information(1); 0024h: "TBD" → "When shipping" NOTES 3 and 4 revised
		19	Table 4.5 SFR Information (5); 0118h: "Timer RE Second Data Register" → "Timer RE Second Data Register / Counter Data Register" 0119h: "Timer RE Minute Data Register" → "Timer RE Minute Data Register / Compare Data Register" 0138h: "TRDMDR" → "TRDMR" 013Bh: "Timer RD Output Master Enable Register" → "Timer RD Output Master Enable Register 1"
		22	Table 5.1 Absolute Maximum Ratings; "Vcc" → "Vcc/AVcc" revised Table 5.2 Recommended Operating Conditions revised
		23	Table 5.3 A/D Converter Characteristics revised
		24	Table 5.4 Flash Memory (Program ROM) Electrical Characteristics revised
		25	Table 5.5 Flash Memory (Data flash Block A, Block B) Electrical revised
		26	Table 5.6 Voltage Detection 0 Circuit Electrical Characteristics revised Table 5.7 Voltage Detection 1 Circuit Electrical Characteristics revised Table 5.8 Voltage Detection 2 Circuit Electrical Characteristics revised
		28	Table 5.11 High-speed On-Chip Oscillator Circuit Electrical Characteristics revised Table 5.12 Low-speed On-Chip Oscillator Circuit Electrical Characteristics revised Table 5.13 Power Supply Circuit Timing Characteristics revised
		29	Table 5.14 Timing Requirements of Clock Synchronous Serial I/O with Chip Select revised
		33	Table 5.15 Timing Requirements of I ² C bus Interface NOTE1 revised
		34	Table 5.16 Electrical Characteristics (1) [Vcc = 5 V] revised
		35	Table 5.17 Electrical Characteristics (2) [Vcc = 5 V] revised
		36	Table 5.18 XIN Input, XCIN Input revised
		37	Table 5.20 Serial Interface revised
		38	Table 5.22 Electrical Characteristics (3) [Vcc = 3 V] revised
		39	Table 5.23 Electrical Characteristics (4) [Vcc = 3 V] revised
		40	Table 5.24 XIN Input, XCIN Input revised
		41	Table 5.26 Serial Interface revised
		42	Table 5.28 Electrical Characteristics (5) [Vcc = 2.2 V] revised
		43	Table 5.29 Electrical Characteristics (6) [Vcc = 2.2 V] revised
		44	Table 5.30 XIN Input, XCIN Input revised Table 5.31 TRAIO Input, INT1 Input revised
		45	Table 5.32 Serial Interface revised Table 5.33 External Interrupt INTi (i = 0, 2, 3) Input

REVISION HISTORY

R8C/24 Group, R8C/25 Group Datasheet

Rev.	Date	Description	
		Page	Summary
2.00	Jul 14, 2006	all pages	"PTLG0064JA-A (64F0G)" package added
		1	1. Overview; "... or a 64-pin molded-plastic FLGA." added
		2, 3	Table 1.1 Functions and Specifications for R8C/24 Group, Table 1.2 Functions and Specifications for R8C/25 Group; Package: "64-pin molded-plastic FLGA" added
		5	Table 1.3 Product Information for R8C/24 Group, Figure 1.2 Type Number, Memory Size, and Package of R8C/24 Group revised
		6	Table 1.4 Product Information for R8C/25 Group, Figure 1.3 Type Number, Memory Size, and Package of R8C/25 Group revised
		7	Figure 1.4 PLQP0052JA-A Package Pin Assignments (Top View); NOTE3 revised
		8	Figure 1.5 PTLG0064JA-A Package Pin Assignments added
		14	Figure 3.1 Memory Map of R8C/24 Group revised
		15	Figure 3.2 Memory Map of R8C/25 Group revised
		23	Table 5.1 Absolute Maximum Ratings; NOTE1 added
		47	Package Dimensions; "PTLG0064JA-A (64F0G)" added
3.00	Feb 29, 2008	all pages	Y version added Factory programming product added
		2, 3	Table 1.1, Table 1.2 Clock; "Real-time clock (timer RE)" added
		5, 7	Table 1.3, Table 1.4 revised
		6, 8	Figure 1.2, Figure 1.3; ROM number "XXX" added
		16, 17	Figure 3.1, Figure 3.2; "Expanded area" deleted
		18	Table 4.1 revised
		26	Table 5.2 NOTE2 revised
		32	Table 5.10; revised, NOTE4 added Table 5.11; Oscillation stability time: Condition "Vcc = 5.0 V, Topr = 25°C" deleted
		38	Table 5.15; I _{IH} , I _L , R _{PULLUP} Condition: "Vcc = 5V" added
		39	Table 5.16; Condition: High-speed on-chip oscillator mode revised
		40	Table 5.17 added
		41	Figure 5.8 revised
		43	Table 5.22; I _{IH} , I _L , R _{PULLUP} Condition: "Vcc = 3V" added
		44	Table 5.23; Condition "Increase during A/D converter operation" added
		45	Figure 5.12 revised
		48	Table 5.29; Condition "Increase during A/D converter operation" added
		49	Figure 5.16 revised